

FEATURES

1. High current capability
2. Low forward voltage drop
3. Low power loss, high efficiency
4. High surge capability
5. High temperature soldering guaranteed
6. Mounting position: any

MECHANICAL DATA

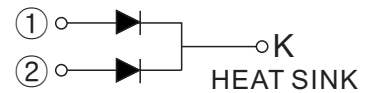
Case: TO-263 molded plastic body

Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

TO-263(D²PAK)



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

MCHARACTERISTICS	SYMBOL	MBRB	MBRB	MBRB	MBRB	MBRB	MBRB	UNITS
		3040CT	3045CT	3060CT	30100CT	30150CT	30200CT	
Maximum repetitive peak reverse voltage	V_{RRM}	40	45	60	100	150	200	V
Maximum RMS voltage	V_{RMS}	28	31.5	42	70	105	140	V
Maximum DC blocking voltage	V_{DC}	40	45	60	100	150	200	V
Maximum average forward rectified current per diode per device	$I_{F(AV)}$	15 30						A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) per device	I_{FSM}	200						A
Maximum instantaneous forward voltage at 15A DC Per leg	V_F	0.70	0.75	0.85	0.90	0.92		V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	I_R	0.1 20			0.05 20			mA
Typical junction capacitance (NOTE 1)	C_J	600	400					pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	45						°C/W
Operating junction temperature range	T_J	-55 to +150				-55 to +175		°C
Storage temperature range	T_{STG}	-55 to +150				-55 to +175		°C

Note: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.
2. PCB. Mounted on 10cm x 10cm x 1mm copper pad areas
3. The typical data above is for reference only.

Typical Characteristics

Fig.1 TYPICAL FORWARD CURRENT DERATING CURVE

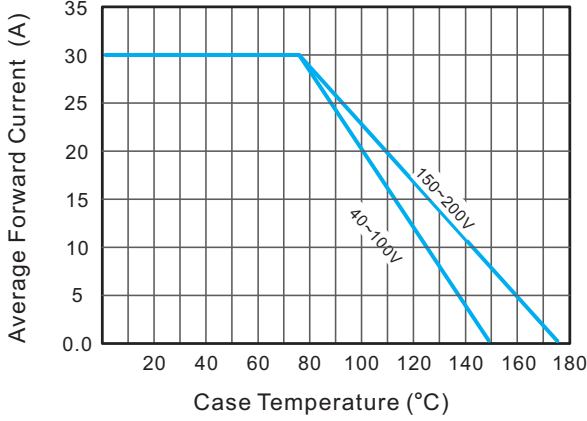


Fig.2 Typical Reverse Characteristics

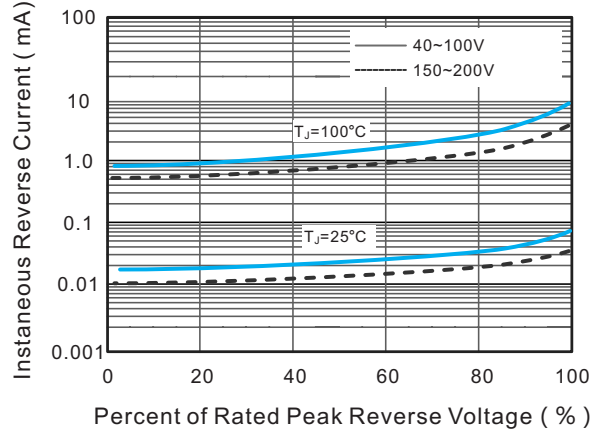


Fig.3 Typical Forward Characteristic

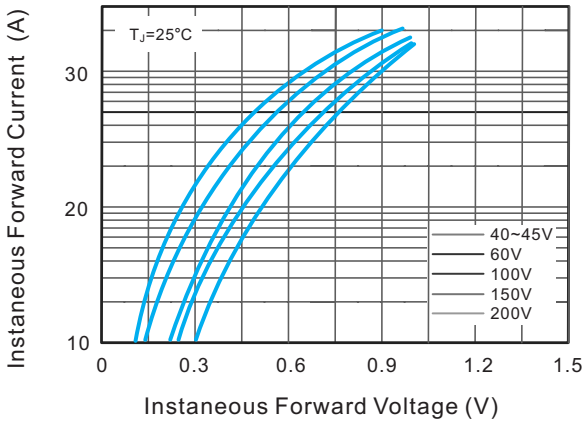


Fig.4 Typical Junction Capacitance

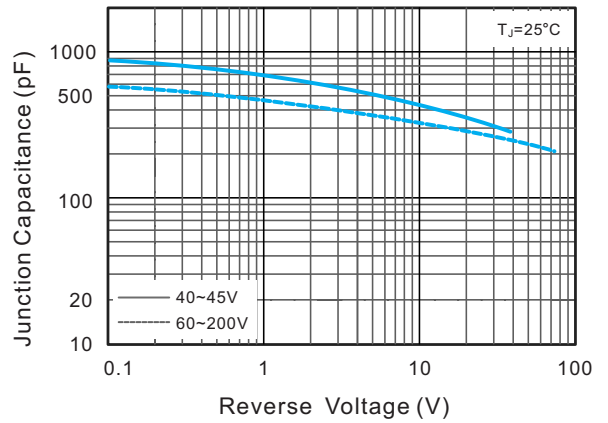


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

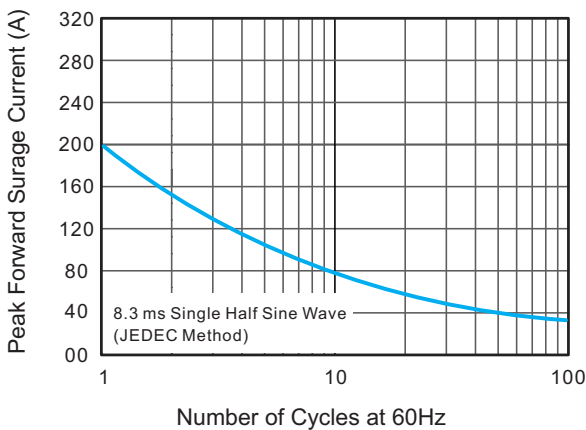
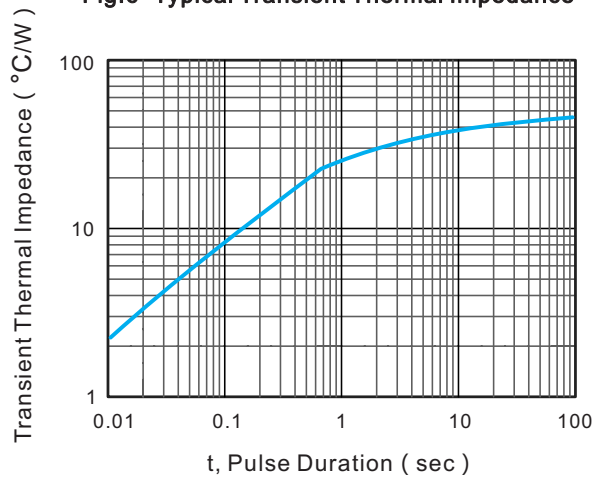
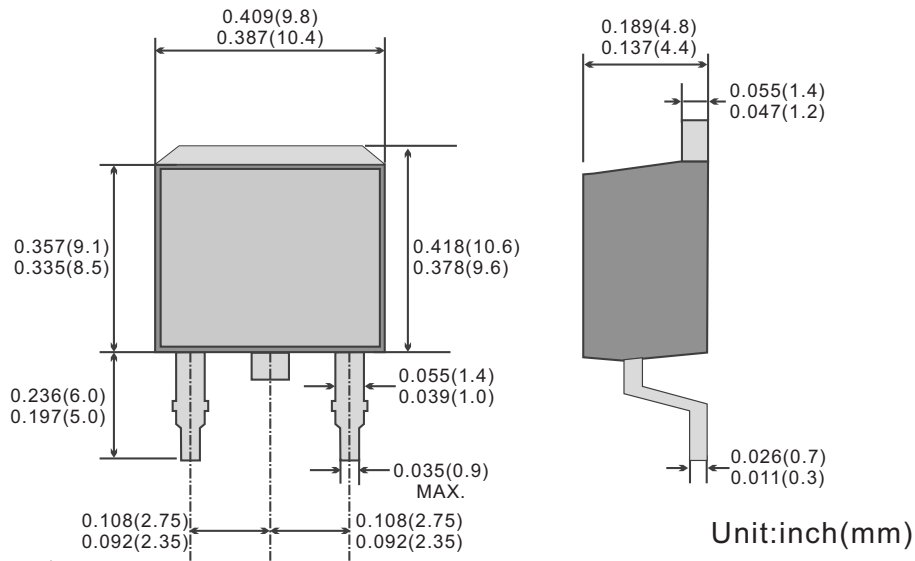


Fig.6- Typical Transient Thermal Impedance

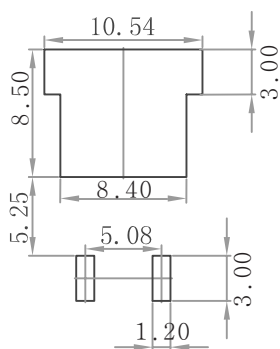


Outline Drawing

TO-263(D²PAK) Package Outline Dimensions



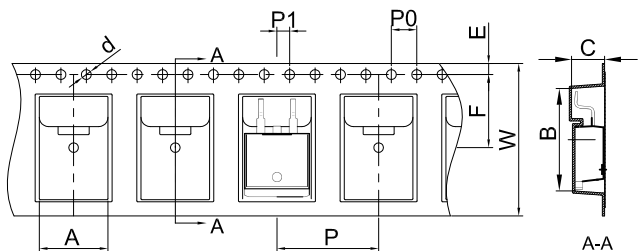
Suggested Pad Layout



Note:

1. Controlling dimension:in/millimeters.
2. General tolerance: ±0.05mm.
3. The pad layout is for reference purposes only.

TO-263 Embossed Carrier Tapeape

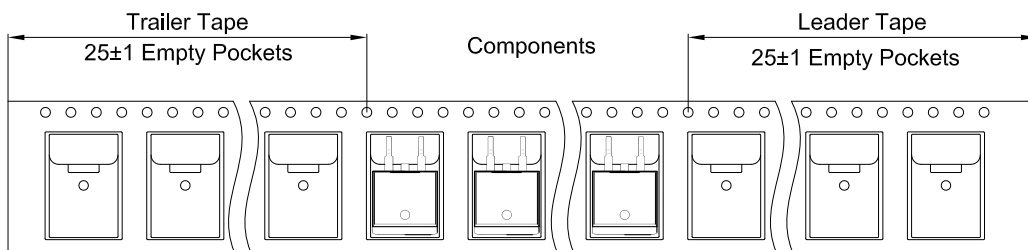


Packaging Description:

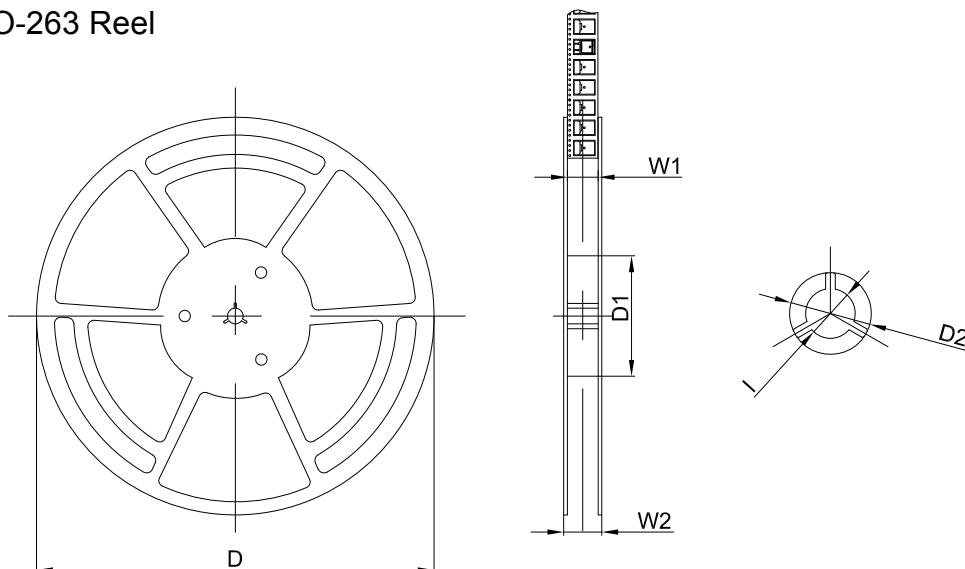
TO-263 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 800 units per 13" or 33.0cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
TO-263	10.80	16.13	5.21	Ø1.55	1.75	11.50	4.00	16.00	2.00	24.00

TO-263 Tape Leader and Trailer



TO-263 Reel



Dimensions are in millimeter						
Reel Option	D	D1	D2	W1	W2	l
13"Dia	Ø330.00	100.00	Ø21.00	24.4	30.4	Ø13.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
800 pcs	13 Inch	1,600 pcs	340×336×66	8,000 pcs	400×353×365	